

N.B.:

1. CVD includes the following processes: directed gas flow out-of-pack deposition, pulsating CVD, controlled nucleation thermal decomposition (CNTD), plasma enhanced or plasma assisted CVD processes.
 2. Pack denotes a substrate immersed in a powder mixture.
 3. The gaseous reactants used in the out-of-pack process are produced using the same basic reactions and parameters as the pack cementation process, except that the substrate to be coated is not in contact with the powder mixture.
- b. *Thermal Evaporation-Physical Vapour Deposition (TE-PVD) is an overlay coating process conducted in a vacuum with a pressure less than 0.1 Pa wherein a source of thermal energy is used to vaporize the coating material. This process results in the condensation, or deposition, of the evaporated species onto appropriately positioned substrates. The addition of gases to the vacuum chamber during the coating process to synthesize compound coatings is an ordinary modification of the process. The use of ion or electron beams, or plasma, to activate or assist the coating's deposition is also a common modification in this technique. The use of monitors to provide in-process measurement of optical characteristics and thickness of coatings can be a feature of these processes. Specific TE-PVD processes are as follows:*
1. *Electron Beam PVD uses an electron beam to heat and evaporate the material which forms the coating;*
 2. *Resistive Heating PVD employs electrically resistive heating sources capable of producing a controlled and uniform flux of evaporated coating species;*
 3. *"Laser" Evaporation uses either pulsed or continuous wave "laser" beams to heat the material which forms the coating;*
 4. *Cathodic Arc Deposition employs a consumable cathode of the material which forms the coating and has an arc discharge established on the surface by a momentary contact of a ground trigger. Controlled motion of arcing erodes the cathode surface creating a highly ionized plasma. The anode can be either a cone attached to the periphery of the cathode, through an insulator, or the chamber. Substrate biasing is used for non line-of-sight deposition.*

N.B.:

This definition does not include random cathodic arc deposition with non-biased substrates.

- c. *Ion Plating is a special modification of a general TE-PVD process in which a plasma or an ion source is used to ionize the species to be deposited, and a negative bias is applied to the substrate in order to facilitate the extraction of the species to be deposited from the plasma. The introduction of reactive species, evaporation of solids within the process chamber, and the use of monitors to provide in-process measurement of optical characteristics and thicknesses of coatings are ordinary modifications of the process.*
- d. *Pack Cementation is a surface modification coating or overlay coating process wherein a substrate is immersed in a powder mixture (a pack), that consists of:*
1. *The metallic powders that are to be deposited (usually aluminium, chromium, silicon or combinations thereof);*
 2. *An activator (normally a halide salt); and*
 3. *An inert powder, most frequently alumina.*
- The substrate and powder mixture is contained within a retort which is heated to between 1,030 K (757°C) and 1,375 K (1,102°C) for sufficient time to deposit the coating.*
- e. *Plasma Spraying is an overlay coating process wherein a gun(spray torch) which produces and controls a plasma accepts powder or wire coating materials, melts them and propels them towards a substrate, whereon an integrally bonded coating is formed. Plasma spraying constitutes either low pressure plasma spraying or high velocity plasma spraying carried out underwater.*

N.B.:

1. *Low pressure means less than ambient atmospheric pressure.*
2. *High velocity refers to nozzle-exit gas velocity exceeding 750 m/s calculated at 293 K (20°C) at 0.1 MPa.*

- f. *Slurry Deposition is a surface modification coating or overlay coating process wherein a metallic or ceramic powder with an organic binder is suspended in a liquid and is applied to a substrate by either spraying, dipping or painting, subsequent air or oven drying, and heat treatment to obtain the desired coating.*
- g. *Sputter Deposition is an overlay coating process based on a momentum transfer phenomenon, wherein positive ions are accelerated by an electric field towards the surface of a target (coating material). The kinetic energy of the impacting ions is sufficient to cause target surface atoms to be released and deposited on an appropriately positioned substrate.*

N.B.:

1. *The Table refers only to triode, magnetron or reactive sputter deposition which is used to increase adhesion of the coating and rate of deposition and to radio frequency (RF) augmented sputter deposition used to permit vapourisation of non-metallic coating materials.*

2. *Low-energy ion beams (less than 5 keV) can be used to activate the deposition.*
- h. *Ion Implantation is a surface modification coating process in which the element to be alloyed is ionized, accelerated through a potential gradient and implanted into the surface region of the substrate. This includes processes in which ion implantation is performed simultaneously with electron beam physical vapour deposition or sputter deposition.*

Statement of Understanding

It is understood that the following technical information, accompanying the table of deposition techniques, is for use as appropriate.

1. "Technology" for pretreatments of the substrates listed in the Table, as follows:
 - a. Chemical stripping and cleaning bath cycle parameters, as follows:
 1. Bath composition
 - a) For the removal of old or defective coatings, corrosion product or foreign deposits;
 - b) For preparation of virgin substrates;
 2. Time in bath;
 3. Temperature of bath;
 4. Number and sequences of wash cycles;
 - b. Visual and macroscopic criteria for acceptance of the cleaned part;
 - c. Heat treatment cycle parameters, as follows:
 1. Atmosphere parameters, as follows:
 - a) Composition of the atmosphere;
 - b) Pressure of the atmosphere;
 2. Temperature for heat treatment;
 3. Time of heat treatment;
 - d. Substrate surface preparation parameters, as follows:
 1. Grit blasting parameters, as follows:
 - a) Grit composition;
 - b) Grit size and shape;
 - c) Grit velocity;
 2. Time and sequence of cleaning cycle after grit blast;
 3. Surface finish parameters;
 - e. Masking technique parameters, as follows:
 1. Material of mask;
 2. Location of mask;
2. "technology" for in situ quality assurance techniques for evaluation of the coating processes listed in the Table, as follows:
 - a. Atmosphere parameters, as follows:
 1. Composition of the atmosphere;
 2. Pressure of the atmosphere;
 - b. Time parameters;
 - c. Temperature parameters;
 - d. Thickness parameters;
 - e. Index of refraction parameters;
3. "Technology" for post deposition treatments of the coated substrates listed in the Table, as follows:
 - a. Shot peening parameters, as follows:
 1. Shot composition;
 2. Shot size;
 3. Shot velocity;
 - b. Post shot peening cleaning parameters;
 - c. Heat treatment cycle parameters, as follows:
 1. Atmosphere parameters, as follows:
 - a) Composition of the atmosphere;
 - b) Pressure of the atmosphere;
 2. Time-temperature cycles;
 - d. Post heat treatment visual and macroscopic criteria for acceptance of the coated substrates;
4. "Technology" for quality assurance techniques for the evaluation of the coated substrates listed in the Table, as follows:
 - a. Statistical sampling criteria;
 - b. Microscopic criteria for:
 1. Magnification;
 2. Coating thickness uniformity;
 3. Coating composition;
 4. Coating and substrates bonding;
 - c. Criteria for optical properties assessment:
 1. Reflectance;
 2. Transmission;
 3. Absorption;
 4. Scatter;
5. "Technology" and parameters related to specific coating and surface modification processes listed in the Table, as follows:
 - a. For Chemical Vapour Deposition:
 1. Coating source composition and formulation;
 2. Carrier gas composition;